

Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Input Control Current, Relay	50	mA
Input Control Current, Detector	100	mA
Total Package Dissipation 1	1	W
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 8.33 mW / °C

Total Power Dissipation (PD):

$$\begin{split} P_D &= P_{HOOKSWITCH} + P_{BRIDGE} + P_{DARLINGTON} + P_{LED} \\ P_D &= (R_{DS}(on)) \; (I^2_L) + 2(V_F)(I_L) + (V_{CE})(I_L) + (V_{LED})(I_F) \end{split}$$

WHERE:

R_{DS}(on) = Maximum relay on resistance

 I_L = Maximum loop current V_F = Maximum diode forward voltage

V_E = Maximum voltage collector to emitter

V_{LED} = Maximum LED forward voltage I_E = Maximum LED current Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C: Relay Section

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Blocking Voltage (Peak)	-	V_L	-	-	350	V _P
Load Current						
Continuous	-	IL	-	-	120	mA_{rms} / mA_{DC}
Peak	t=10ms	I _{LPK}	-	-	400	mA _P
On-Resistance	I _L =120mA	R _{ON}	-	-	15	Ω
Off-State Leakage Current	V _L =350V, T _J =25°C	I _{LEAK}	-	-	1	μΑ
Switching Speeds						
Turn-On	I 5m / \/ 10\/	t _{on}	-	-	3	ma
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	3	ms
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics			1		1	1
Input Control Current (to Activate)	I _L =120mA	I _F	-	-	5	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V_R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ

Electrical Characteristics @25°C: Darlington Transistor Section

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Collector-Emitter Voltage	I _C =10mA _{DC} , I _B =0mA	V_{CEO}	40	-	-	V
Collector Current, Continuous	V _C =3.5V	I _C	-	-	120	mA
Power Dissipation	-	P_{D}	-	-	500	mW
Off-State Collector-Emitter Leakage Current	V _{CE} =10V, I _B =0mA	I _{CEX}	-	-	1	μΑ
DC Current Gain	$V_{CE}=10V_{DC}$, $I_{C}=120mA$	h _{FE}	10,000	-	-	-
Saturation Voltage	I _C =120mA	V _{CE(sat)}	-	-	1.5	V
Total Harmonic Distortion	I _C =40mA, f _O =300Hz @ -10dBm	-	-	-	-80	dB



Electrical Characteristics @25°C: Detector Section

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Phototransistor Blocking Voltage	I _C =10μΑ	BV _{CEO}	20	50	-	V
Phototransistor Dark Current	V _{CE} =5V, I _F =0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _F =16mA , I _C =2mA	V _{SAT}	-	0.3	0.5	V
Current Transfer Ratio	I _F =6mA, V _{CE} =0.5V	CTR	33	400	-	%
Input Characteristics		I		•		'
Input Control Current	$I_C=2mA, V_{CE}=0.5V$	I _F	-	2	6	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Input Current (Detector Must be Off)	$I_C=1\mu A, V_{CE}=5V$	I _F	5	25	-	μΑ

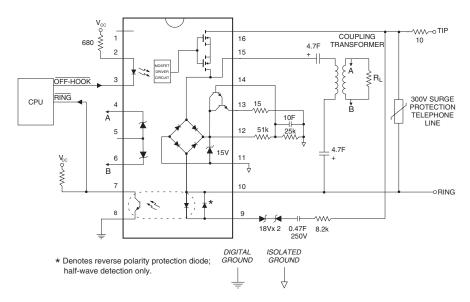
Electrical Characteristics @25°C (Unless Otherwise Noted): Bridge Rectifier Section

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Reverse Voltage	-	V_{RD}	-	-	100	V
Forward Voltage Drop	I _{FD} =120mA	V_{FD}	-	-	1.5	V
Reverse Leakage Current	T _J =25°C, V _R =100V	1	-	-	10	
	T _J =85°C	^I RD	-	-	50	— μA
Forward Current						
Continuous	-		-	-	140	mΛ
Peak	t=10ms	I _{FD}	-	-	500	— mA

Electrical Characteristics @25°C: Zener Diodes

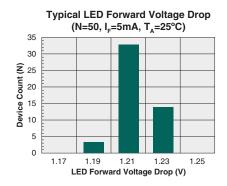
Parameter	Conditions	Symbol	Min	Тур	Max	Units
Zener Voltage Between Pins 4&5 and Pins 6&5	I _{ZT} =20mA	V _Z	-	4.3	-	V
Zener Voltage Between Pins 12&11	I _{ZT} =20mA	V _Z	-	15	-	V
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF
Input to Output Isolation	-	V _{I/O}	3750	-	-	V _{rms}

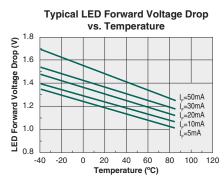
EXAMPLE CIRCUIT

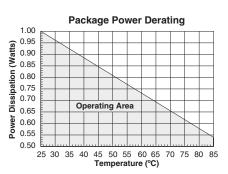




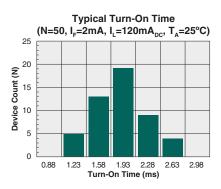
DEVICE PERFORMANCE DATA*

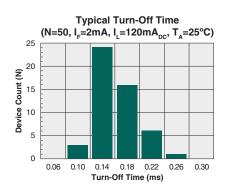


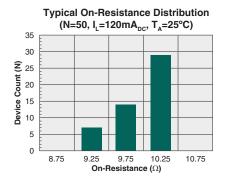


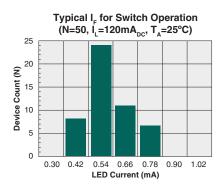


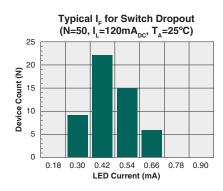
RELAY PERFORMANCE DATA*

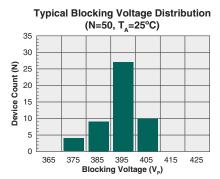








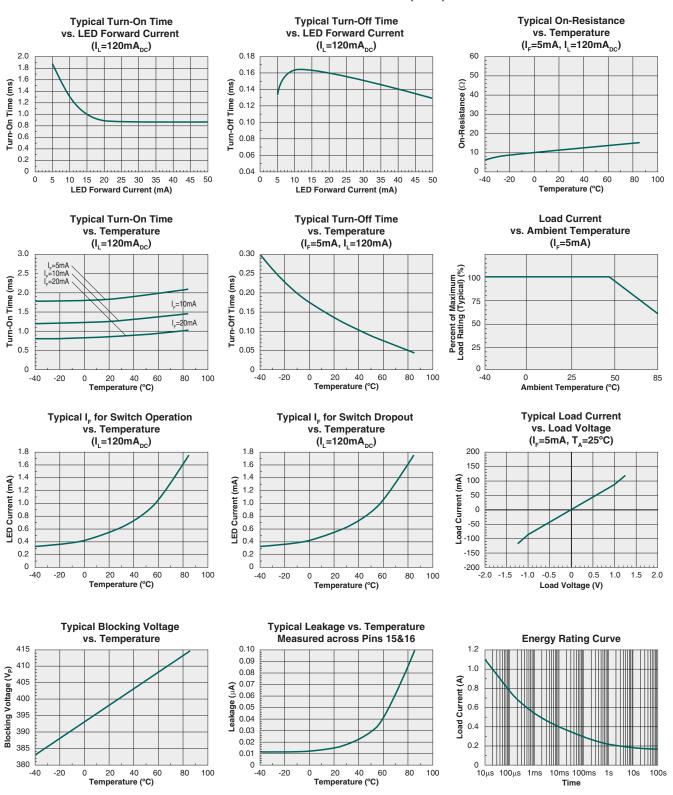




^{*} Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.



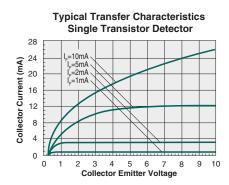
RELAY PERFORMANCE DATA (cont)*

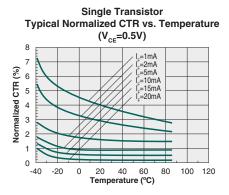


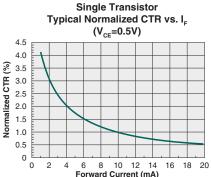
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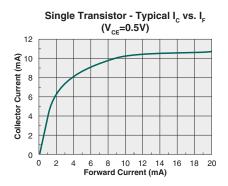


PHOTOTRANSISTOR PERFORMANCE DATA*

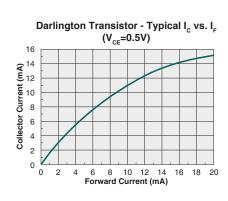


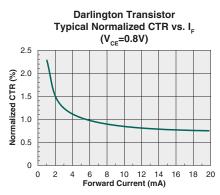


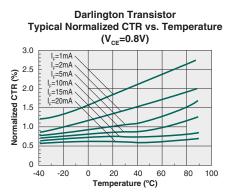


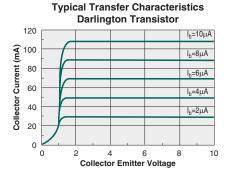


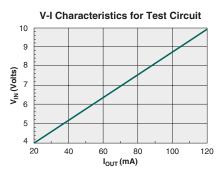
DARLINGTON PERFORMANCE DATA*











^{*} Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.



Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingression, IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

Device	Moisture Sensitivity Level (MSL) Classification
ITC135P	MSL 3

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the IPC/JEDEC J-STD-020 Classification Temperature (T_C) and the maximum dwell time the body temperature of these surface mount devices may be (T_C - 5)°C or greater. The Classification Temperature sets the Maximum Body Temperature allowed for these devices during reflow soldering processes.

Device	Classification Temperature (T _c)	Dwell Time (t _P)	Max Reflow Cycles
ITC135P	245°C	30 seconds	3

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.









MECHANICAL DIMENSIONS

ITC135P 10.160±0.381 **PCB Land Pattern** (0.400±0.015) 0.254 ±0.0127 PIN 16 (0.010±0.0005) 10.363±0.127 (0.408±0.005) 9.30 0.635 X 45° 7.493±0.127 (0.366)(0.025 X 45°) 1.016 TYP (0.295±0.005) 1.90 (0.040 TYP) (0.075)PIN 1 1.27 1.270 TYP (0.050)(0.050 TYP) 2.057±0.051 0.60 (0.081±0.002) (0.024)**DIMENSIONS** mm (inches) 0.406 TYP (0.016 TYP) Lead to Package Standoff: 8.890 TYP NOTES:

MIN: 0.0254 (0.001)

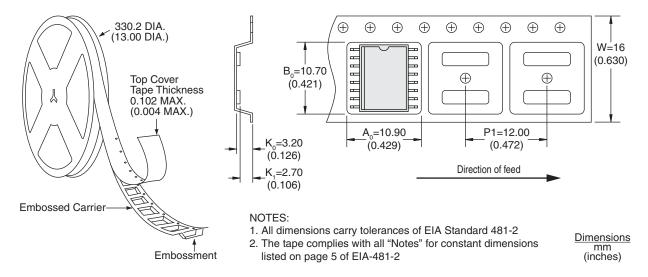
MAX: 0.102 (0.004)

ITC135PTR Tape & Reel

(0.350 TYP)

0.508±0.1016

(0.020±0.004)



1. Coplanarity = 0.1016 (0.004) max.

(1000 microinch maximum).

2. Leadframe thickness does not include solder plating

For additional information please visit our website at: https://www.ixysic.com



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